

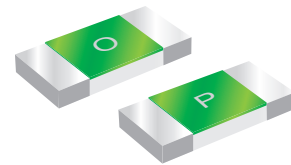
Fast Acting | 0.126x0.064 inch Thick Film Chip Fuses

1206FA-xxxD Series



Features

- High inrush current withstanding capability
- AEC-Q200 Automotive Grade Certified
- Compatible with reflow and wave solder
- Ceramic and glass construction
- Excellent environmental integrity
- One time positive disconnect
- Lead Free and Halogen free material



Electrical Characteristics

Amp Rating	% of Amp Rating	Opening Time
12~50A	100%	4 Hours Min.
12~50A	350%	5 Seconds Max.
12~30A	1000%	0.2ms~20ms

Specification

Part Number	Ampere Rating (A)	Interrupting Rating	Voltage Rating	Typical Cold Resistance (Ohms)	Typical Melting I ² t (A ² Sec)	Typical Voltage Drop (V)	Marking Code
1206FA-12AD	12	150A @ 32Vdc 300A @ 24Vdc		0.0053	40	0.080	W
1206FA-15AD	15			0.0045	45	0.085	Y
1206FA-20AD	20			0.0034	50	0.080	Q
1206FA-25AD	25			0.0016	60	0.090	L
1206FA-30AD	30			0.0013	100	0.090	Z
1206FA-40AD	40	200A @ 32Vdc		0.00085	240	0.095	XL
1206FA-50AD	50	200A @ 24Vdc		0.00070	260	0.095	50

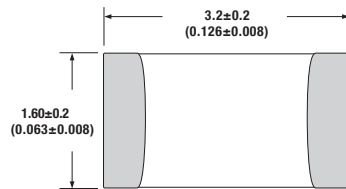
- DC Interrupting Rating (Measured at rated voltage, time constant of less than 50 microseconds, battery source)
- DC Cold Resistance are measured at <10% of rated current in ambient temperature of 25 °C
- Typical Pre-arcing I²t are measured at 10In Current
Choice fuse for surge application (USB charger etc.), make sure the I²t of fuse is 4 times than surge.
- Specifications are subject to change without notice. Application testing is strongly recommended.

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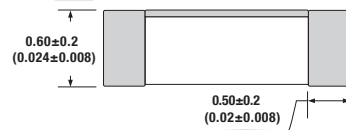
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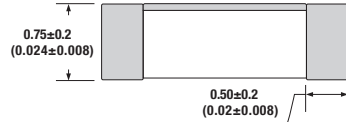
Dimension Unit: mm/inch



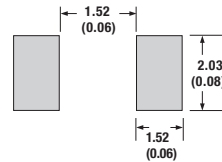
12A-30A



40A-50A



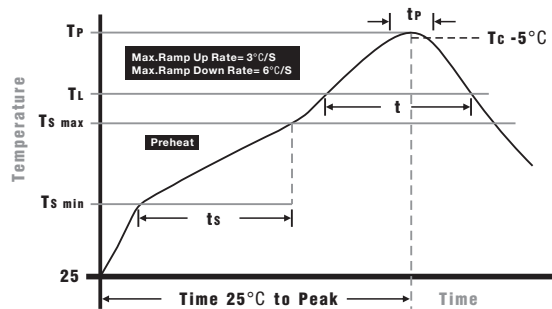
Pad layout



Packaging

- Quantity: 3,000pcs
- 8mm wide tape on 178mm(7 inch) diameter reel -specification EIA Standard 481.

Soldering Parameters

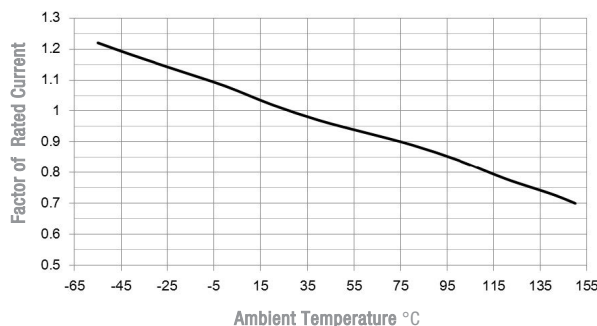


Wave Soldering: 260°C, 10 seconds max.
Infrared Reflow: 260°C, 30 seconds max.

IR Reflow Profile

Preheat Heat	
Temperature min (T _{min})	150°C
Temperature max (T _{max})	200°C
Time (T _{min} to T _{max}) (ts)	60 - 120 seconds
Average ramp-up rate (T _{max} to T _p)	3°C/second max.
Liquidous temperature (T _L)	217°C
Time at liquidous (t _L)	60 - 150 seconds
Peak temperature (T _p)	260±0/-5°C
Time within 5°C of actual peak Temperature (t _p)	10 - 30 seconds
Average ramp-down rate (T _p to T _{max})	6°C/second max.
Time 25 °C to peak temperature	8 minutes max.

Temperature Derating Curve



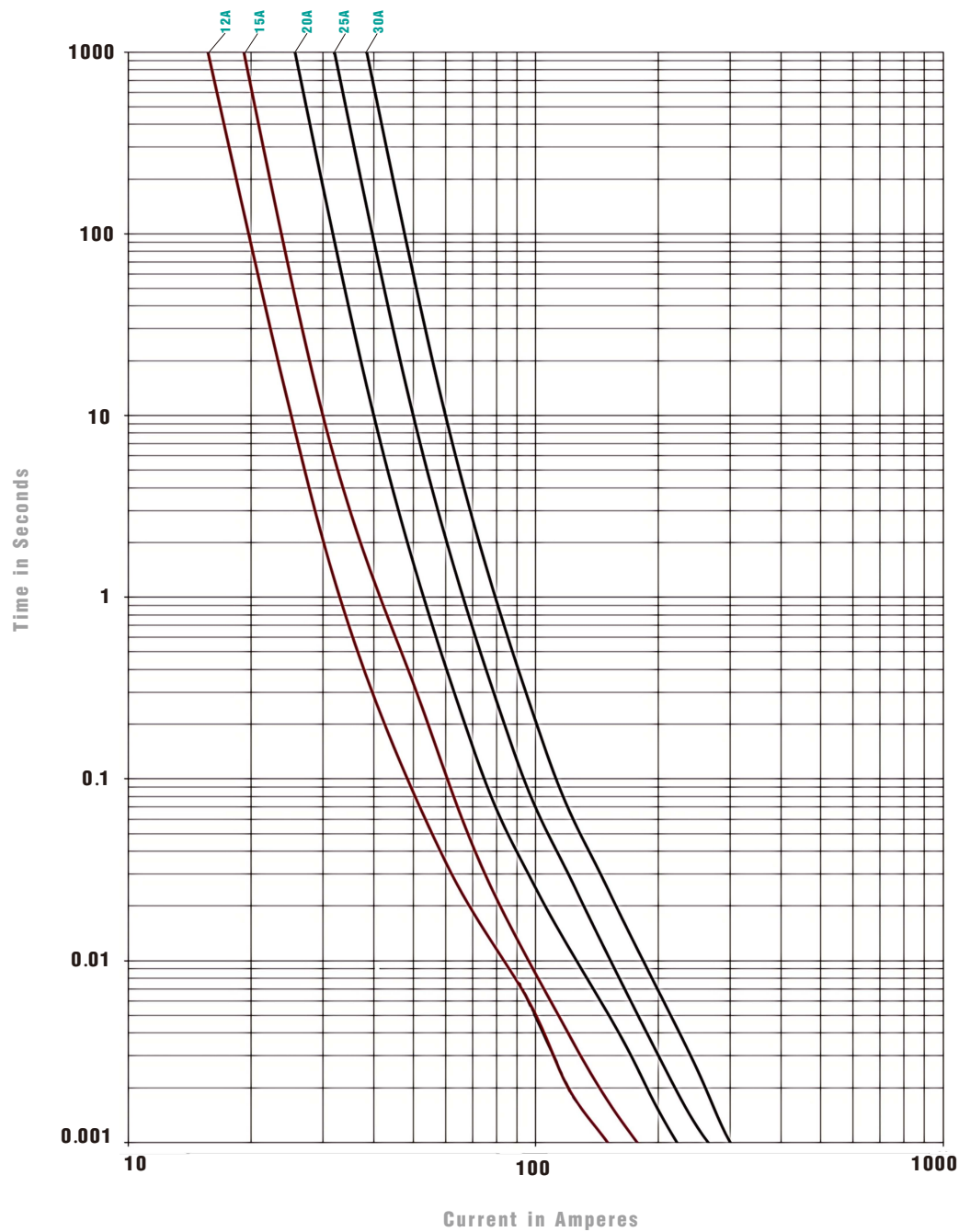
- Normal ambient temperature: 23±3°C
- Operating temperature: -55 ~ 150 °C, with proper correction factor applied

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Average Time Current Curves



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